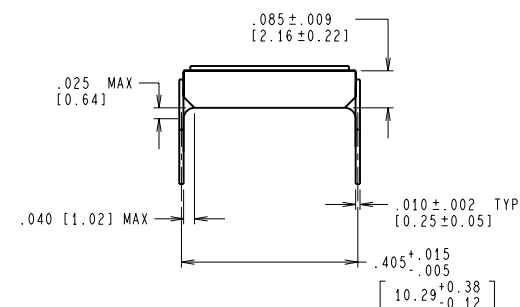
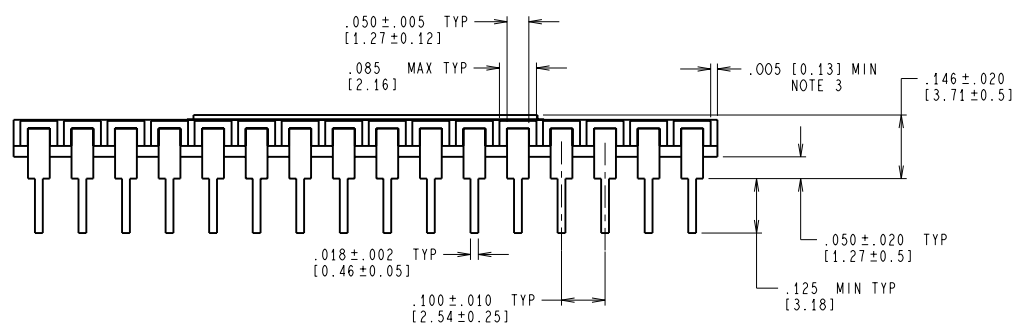
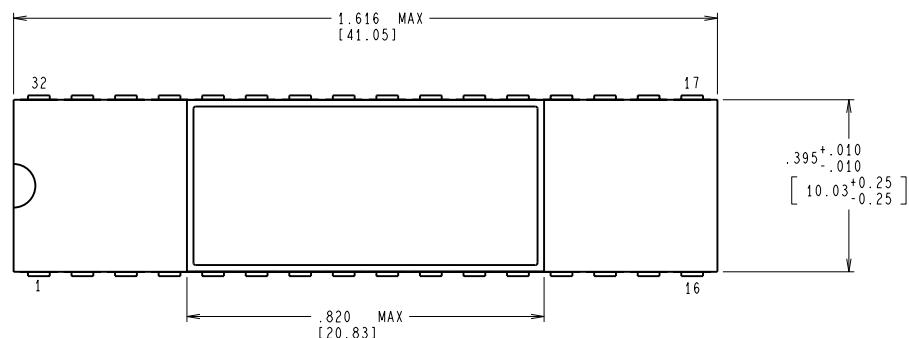


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL.	10482	07/31/94	DEG/



CONTROLLING DIMENSION IS INCH
VALUES IN [] ARE MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED.

- LEAD FINISH TO BE ONE OF THE FOLLOWING:
 - 200 MICROINCHES/5.08 MICROMETERS MINIMUM SOLDER MEASURED AT THE CREST OF THE MAJOR FLATS.
 - 50 MICROINCHES/1.27 MICROMETERS MINIMUM GOLD OVER 50 TO 350 MICROINCHES/1.27 TO 8.89 MICROMETERS NICKEL UNDERPLATE.
- LEAD FINISH, NICKEL UNDERPLATE AND BASIS METAL SHALL CONFORM TO THE REQUIREMENTS OF MIL-M-38510.
- DIMENSION .005 IN/0.13mm MINIMUM SHALL BE MEASURED FROM THE EDGE OF THE FURTHEST EXTENSION OF THE METAL PAD OR LEAD.
- NO JEDEC REGISTRATION AS OF 7/94.

APPROVALS		DATE		 National Semiconductor 2900 Semiconductor dr, Santa Clara, CA 95052-8090			
DRAWN <i>D.E.Grady</i>		07/31/94					
DFTG. CHK.							
ENGR. CHK.							
APPROVAL							
				DIP, SIDEBRAZED CERAMIC, 32 LEAD .400 CENTERS			
 PROJECTION INCH [MM]				SCALE N/A	SIZE C	DRAWING NUMBER MKT-DA32A	REV A
				DO NOT SCALE DRAWING		SHEET 1 of 1	